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Addendum to
M68000
User Manual

August 7, 1997

This addendum to the *M68000UM/AD User's Manual*, Revision 8, provides corrections to the o
well as additional information. This document and other information on this product is maintaine
Wide Web at http://www.motorola.com/68000.

OVERVIEW

This manual includes hardware details and programming information for the MC68HC000, the
the MC68EC000, and the MC68SEC000. For ease of reading, the name M68000 MPUs will be
referring to all processors. Refer to M68000PM/AD, *M68000 Programmer's Reference Manual*,
information on the MC68000 instruction set.

The four microprocessors are very similar to each other and all contain the following features:

- Sixteen 32-Bit Data and Address Registers
- 16-Mbyte Direct Addressing Range
- Program Counter
- 6 Instruction Types
- Operations on Five Main Data Types
- Memory-Mapped Input/Output (I/O)
- 14 Addressing Modes

The following processors contain additional features:

- MC68HC001/MC68EC000/MC68SEC000
  - — Statically selectable 8- or 16-bit data bus
- MC68HC000/MC68EC000/MC68HC001/MC68SEC000
  - — Low power

The primary features of the MC68SEC000 embedded processor include the following:

- Direct Replacement for the MC68EC000
  - — Pin-for-pin compatibility with the MC68EC000 in the plastic QFP and TQFP packages
  - — Vast selection of existing third-party development tools for the MC68EC000 support the MC68SEC000
  - — Software written for the MC68EC000 will run unchanged on the MC68SEC000
- Power Management
  - — Low-power HCMOS technology
  - — Static design allows for stopping the processor clock
  - — 3.3V or 5V operation
  - — Typical 0.5µA current consumption at 3.3V in sleep mode
- Software Strength
  - — Fully upward object-code compatible with other M68000 Family products
  - — M68000 architecture allows effective assembly code with a C compiler
- Upgrade
  - — Fully upward code-compatible with higher performance 680x0 and 68300 Family members
  - — ColdFire® code-compatible with minor modifications

1. MC68HC000

The primary benefit of the MC68HC000 is reduced power consumption. The device dissipates less pow an order of magnitude) than the NMOS MC68000.

The MC68HC000 is an implementation of the M68000 16/-32 bit microprocessor architecture. The MC68HC000 has a 16-bit data bus implementation of the MC68000 and is upward code-compatible w MC68010 and the MC68020 32-bit implementation of the architecture.

1.1 MC68HC001

The MC68HC001 provides a functional extension to the MC68HC000 HCMOS 16-/32-bit microprocess the addition of statically selectable 8- or 16-bit data bus operation. The MC68HC001 is object-code com with the MC68HC000. You can migrate code written for the MC68HC001 without modification to any m of the M68000 Family.

1.2 MC68EC000

The MC68EC000 is an economical high-performance embedded controller designed to suit the needs cost-sensitive embedded-controller market. The HCMOS MC68EC000 has an internal 32-bit architectu is supported by a statically selectable 8- or 16-bit data bus. This architecture provides a fast and effic processing device that can satisfy the requirements of sophisticated applications based on high-level languages.

The MC68EC000 is fully object-code compatible with the MC68000. You can migrate code written for MC68EC000 without modification to any member of the M68000 Family.

The MC68EC000 brings the performance level of the M68000 Family to cost levels previously associat 8-bit microprocessors. The MC68EC000 benefits from the rich M68000 instruction set and its related hig density with low memory bandwidth requirements.

1.3 MC68SEC000

The MC68SEC000 is a cost-effective static embedded processor engineered for low-power applicatio addition to providing the substantial cost and performance benefits of the MC68EC000, the low-powe of the MC68SEC000 provides significant advantages in power consumption and power management typical current consumption of the MC68SEC000 is only 0.5µA in static standby mode and 15.0mA in 3.3V operation. The MC68SEC000 operates in either 3.3V or 5.0V systems. The remarkably low pow consumption, small footprint packages, and static implementation are combined in the MC68SEC000 power applications such as portable measuring equipment, electronic games, and battery-operated ha consumer products.

The HCMOS MC68SEC000's static architecture is a direct replacement for the MC68EC000, which of lowest cost entry point to 32-bit processing. The internal 32-bit architecture provides fast and efficient processing that satisfies the requirements of sophisticated applications based on high-level language

All of the existing third-party developer tools widely available for the MC68EC000 will directly support MC68SEC000. You can find detailed descriptions of these tools in the *High Performance Embedded S Source Catalog*.

2.0 SIGNAL DESCRIPTION

Change Figure 3-3 on Page 3-2.

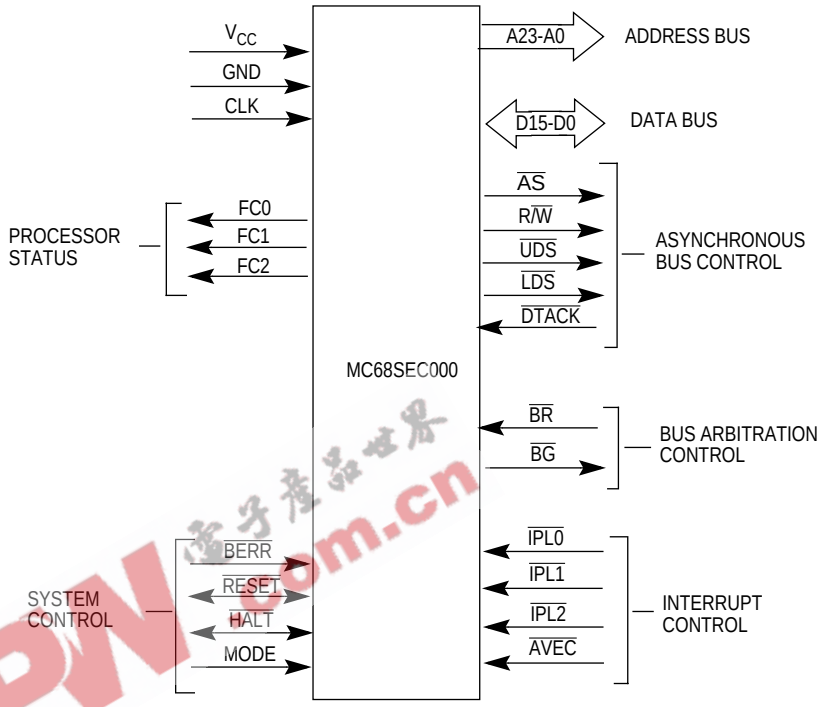


Figure 1. Input and Output Signals (MC68EC000 and MC68SEC000)

2.1 Data Bus (D15-D0)

In Section 3.2 on page 3-4, replace “The MC68EC000 and MC68HC001 use D7-D0 in 8-bit mode, a D8 are undefined.” with “Using the MC68HC001, MC68EC000, and MC68SEC000 mode pin, you statically select either 8- or 16-bit modes for data transfer. The MC68EC000, MC68SEC000, and MC68HC001 use D7-D0 in 8-bit mode. D15-D8 are undefined.”

2.2 Bus Arbitration Control

In Section 3.4 on page 3-5, the sentence “In the 48-pin version of the MC68008 and MC68EC000, n available for the bus grant acknowledge signal; this microprocessor uses a two-wire bus arbitration scheme.” should read “In the 64-pin MC68EC000 and MC68SEC000, no pin is available for the bu acknowledge signal. These microprocessors use a two-wire bus arbitration scheme.”

2.3 System Control

The Mode subsection heading of Section 3.6 on page 3-7 should read ‘‘Mode (MODE) (MC68HC0 68EC000/68SEC000).’’

2.4 MC68SEC000 Low-Power Mode

Add the following to Sections 4 and 5, Bus Operation.

The MC68SEC000 has been redesigned to provide fully static- and low-power operation. This sect describes the recommended method for placing the MC68SEC000 into a low-power mode to reduc

power consumption to its quiescent value[1] while maintaining the internal state of the processor. Th
low-power mode described below will be routinely tested as part of the MC68SEC000 test vectors p
by Motorola.

To successfully enter the low-power mode, the MC68SEC000 must first be in the supervisor mode
recommended method for entering the low-power mode is to use the TRAP instruction, which caus
processor to begin exception processing, thus entering the supervisor mode. External circuitry sho
accomplish the following steps during the trap routine:

1. Externally detect a write to the low-power address. You select this address which can be any a
in the 16 Mbyte addressing range of the MC68SEC000. A write to the low-power address ca
detected by polling A23–A0, R/$\overline{W}$, and FC2–FC0. When the low-power address is detected,
a logic low, and the function codes have a five (101) on their output, the processor is writing
low-power address in supervisor mode and user-designed circuitry should assert the
ADDRESS_MATCH signal shown in Figure 2 and Figure 3.

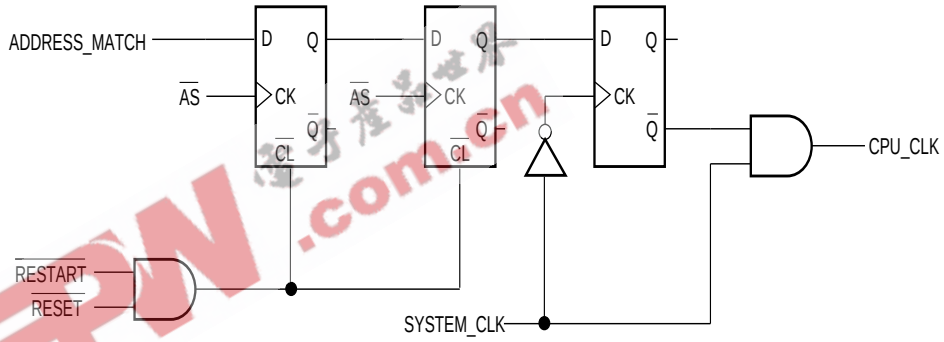


Figure 2. MC68SEC000 Low-Power Circuitry for 16-Bit Data Bus

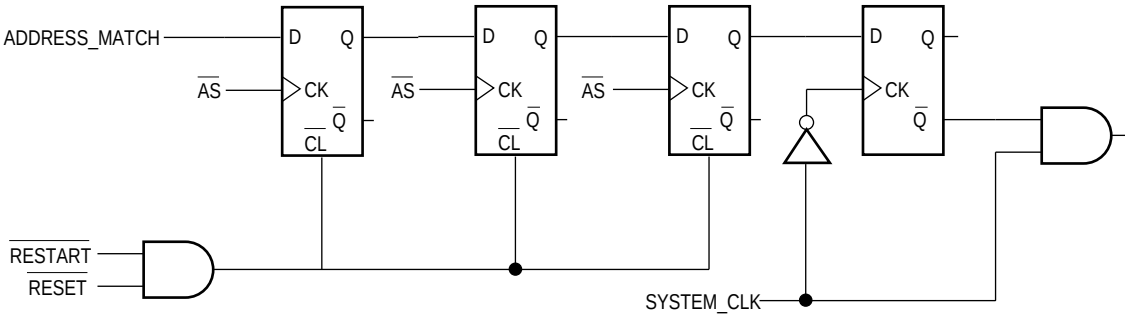


Figure 3. MC68SEC000 Low-Power Circuitry for 8-Bit Data Bus

2. Execute the STOP instruction. The external circuitry shown in Figure 2 and Figure 3 will cou
number of bus cycles starting with the write to the low-power address and will stop the proc
clock on the first falling edge of the system clock after the bus cycle that reads the immedia
of the STOP instruction. Figure 3 has one more flip-flop than Figure 2 because the MC68SE

[1] The preliminary specification for the MC68SEC000's current drain while in the low-power mode is Idd < 2µA for 3.3V oper
Idd < 5µA for 5.0V operation.

8-bit mode requires two bus cycles to fetch the immediate data of the STOP instruction. Afte
processor clock is disabled, it is often necessary to disable the clock to other sections of your
This can be done, but be careful that runt clocks and spurious glitches are not presented to
MC68SEC000. A timing diagram is shown in Figure 4.

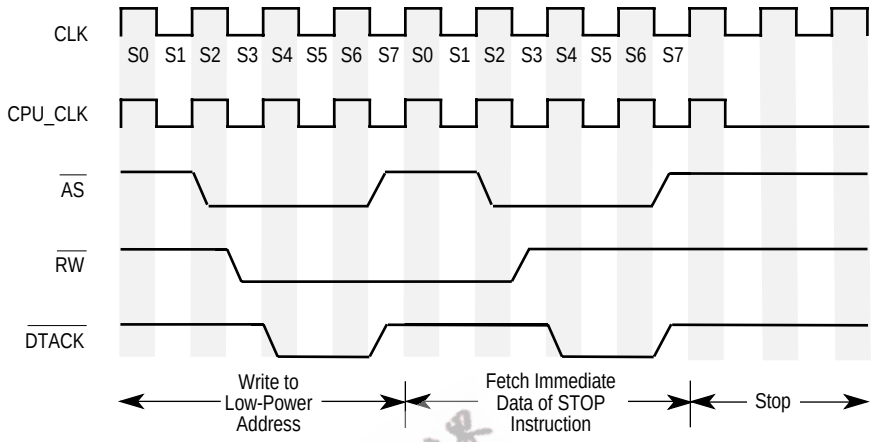


Figure 4. MC68SEC000 Clock Stop Timing for 16-Bit Data Bus

Note: While the MC68SEC000 is in the low-power mode, all inputs must be driven to V_{DD} or V_{SS}, or
pull-up or pull-down resistor.

3. This step is optional depending on whether your applications require the MC68SEC000 sign
three-state capability to be placed into a high-impedance state. To place the MC68SEC000
three-state condition, the proper method for arbitrating the bus (as described in **5.2 Bus Arbi**
in the *M68000 User's Manual, Rev 8*) should be completed during the fetch of the status regis
for the STOP instruction. A timing diagram with the bus arbitration sequence is shown in Fig

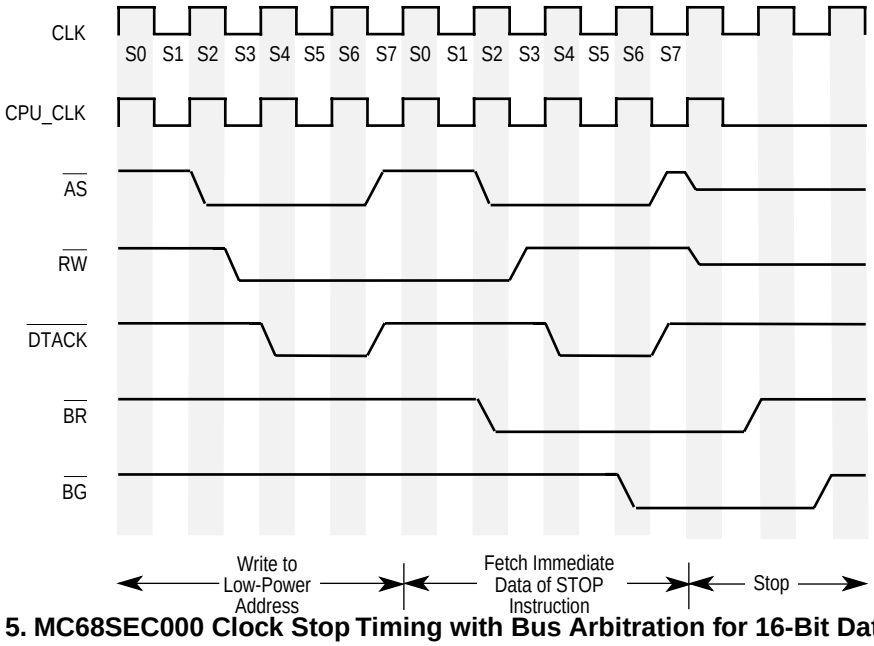


Figure 5. MC68SEC000 Clock Stop Timing with Bus Arbitration for 16-Bit Data Bus

After the previous steps are completed, the MC68SEC000 will remain in the low-power mode recognizes the appropriate interrupt . External logic will also have to poll IPLB2–IPLB0 to detect the interrupt. When the correct interrupt level is received, the following steps will bring the processor ou low-power mode:

1. Restart the system clock if it was stopped.
2. Wait for the system clock to become stable.
3. Assert the $\overline{\text{RESTART}}$ signal. This will cause the processor's clock to start on the next falling the system clock. Figure 6 shows the timing for bringing the processor out of the low-power Both the $\overline{\text{RESTART}}$ and $\overline{\text{RESET}}$ signals are subject to the asynchronous setup time as spec the Electrical Characteristics section of this addendum.

WARNING

The system clock must be stable before the $\overline{\text{RESTART}}$ signal is asserted to prevent glitches in the clock. An unstable clock can cause unpredictable results in the MC68SEC000.

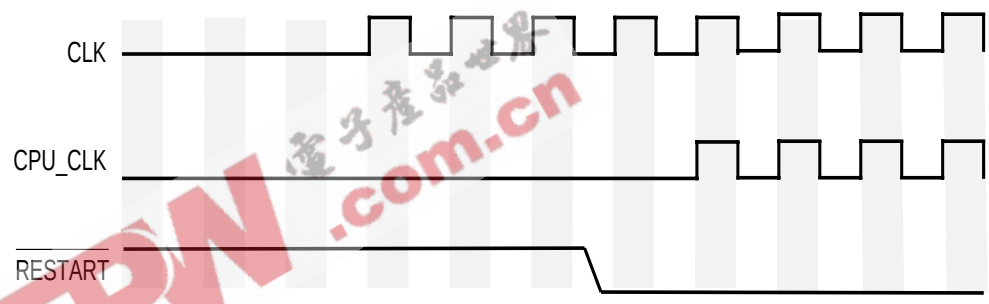


Figure 6. MC68SEC000 Clock Start Timing

4. If the MC68SEC000 was placed in a three-state condition, the $\overline{\text{BR}}$ signal must be negated bef processor can begin executing instructions.

An example trap routine is as follows:

```
TRAP_x   MOVE.B #0,$low_power_address    /* Write that causes ADDRESS_MATCH to ass
         STOP #$2000                     /* STOP instruction with desired interrupt mask
         RTE                             /* Return from the exception */
```

The first instruction (MOVE.B #0,$low_power_address) writes a byte to the low-power address tha cause the external circuitry to begin the sequence that will stop the processor's clock. The second instruction (STOP #$2000) loads the SR with the immediate data. This lets you set the interrupt tha cause the processor to come out of the low-power mode. The final instruction (RTE) tells the proce return from the exception and resume normal processing.

3.0 MC68SEC000 ELECTRICAL SPECIFICATIONS

Add to the following table to Section 10.1.

3.1 MC68SEC000 MAXIMUM RATINGS

RATING	SYMBOL	VALUE	UN
Supply Voltage	V_{CC}	–0.3 to 6.5	V
Input Voltage	V_{in}	–0.5 to 6.5	V
Maximum Operating Temperature Range Commercial Extended "C" Grade	T_A	T_L to T_H 0 to 70 –40 to 85	°C
Storage Temperature	Tstg	–55 to 150	°C

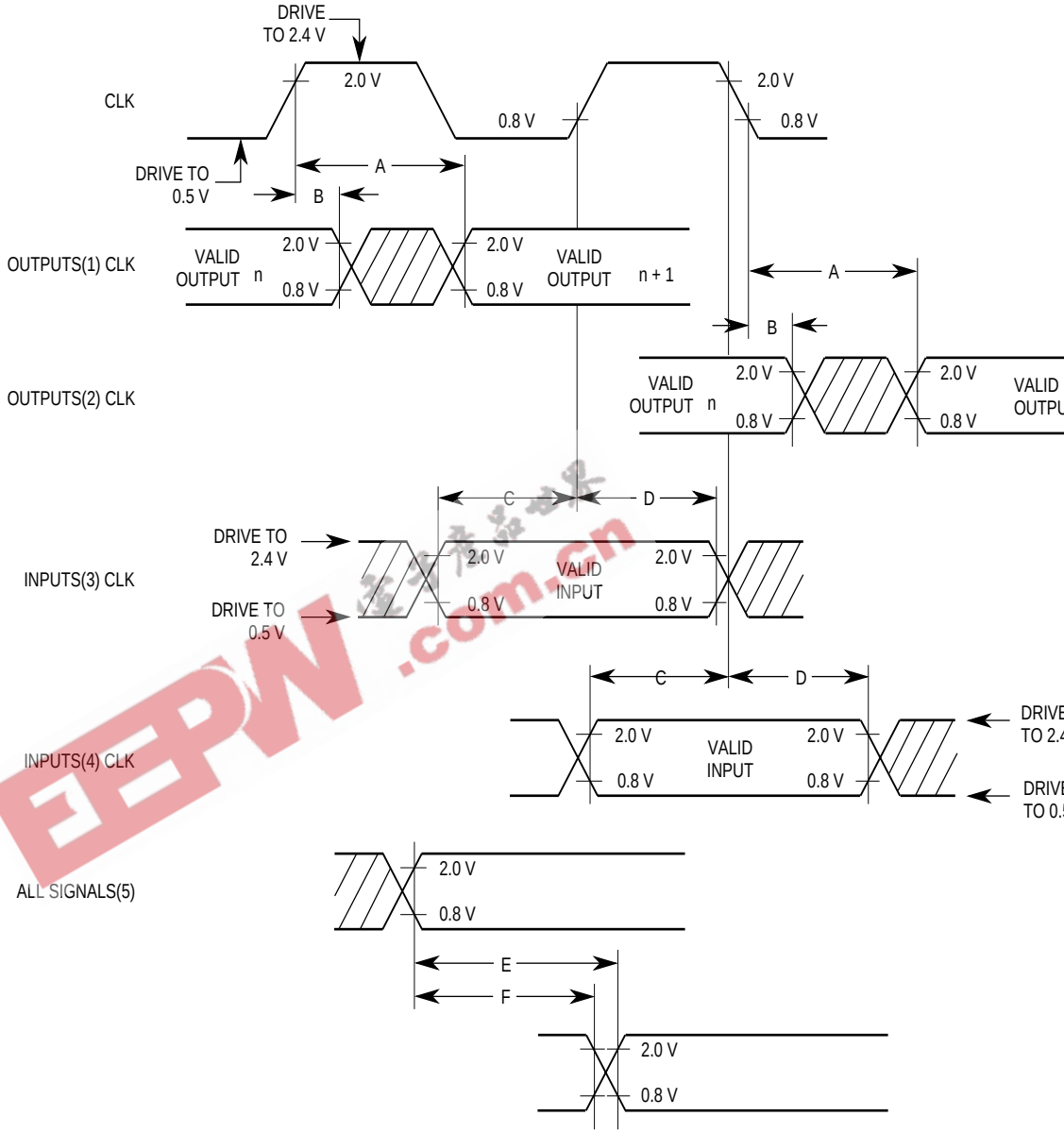
3.2 CMOS CONSIDERATIONS

The following change should be made to Section 10.4, CMOS Considerations.

"Although the MC68HC000 and MC68EC000 is implemented with input protection diodes, care sh exercised to ensure that the maximum input voltage specification is not exceeded." should read "A the MC68HC000, MC68EC000, and MC68SEC000 are implemented with input protection diodes, careful not to exceed the maximum input voltage specification."

4.0 MC68SEC000 AC ELECTRICAL SPECIFICATIONS

Replace Figure 10-2 on page 10-6 with Figure 7.



NOTES:
1. This output timing is applicable to all parameters specified relative to the rising edge of the clock.
2. This output timing is applicable to all parameters specified relative to the falling edge of the clock.
3. This input timing is applicable to all parameters specified relative to the rising edge of the clock.
4. This input timing is applicable to all parameters specified relative to the falling edge of the clock.
5. This timing is applicable to all parameters specified relative to the assertion/negation of another signal.

LEGEND:
A. Maximum output delay specification.
B. Minimum output hold time.
C. Minimum input setup time specification.
D. Minimum input hold time specification.
E. Signal valid to signal valid specification (maximum or minimum).
F. Signal valid to signal invalid specification (maximum or minimum).

Figure 7. Drive Levels and Test Points for AC Specifications - applies to all parts

5.0 MC68SEC000 DC ELECTRICAL SPECIFICATIONS

Add the following table to Section 10.13 on page 10-23.

(V_{CC} = 5.0 Vdc ±5%, 3.3 Vdc ±10%,; GND = 0 Vdc; $T_A = T_L$ to T_H)

CHARACTERISTIC	SYMBOL	3.3 V		5.0 V	
		MIN	MAX	MIN	MAX
Input High Voltage	V_{IH}	2.0	V_{CC}	2.0	V_{CC}
Input Low Voltage	V_{IL}	GND	0.8	GND – 0.5	0.8
Input Leakage Current $\overline{BERR}$, $\overline{BR}$, $\overline{DTACK}$, CLK, $\overline{IPL2}$-$\overline{IPL0}$, $\overline{AVEC}$ MODE, $\overline{HALT}$, $\overline{RESET}$	Iin	—	2.5 20	—	2.5 20
Three-State (Off State) Input Current	I_{TSI}	—	2.5	—	2.5
Output High Voltage	V_{OH}	2.4	—	V_{CC}–0.75	—
Output Low Voltage	V_{OL}				
(IOL = 1.6 mA) $\overline{HALT}$		—	0.5	—	0.5
(IOL = 3.2 mA) A23–A0, $\overline{BG}$, FC2–FC0		—	0.5	—	0.5
(IOL = 5.0 mA) $\overline{RESET}$		—	0.5	—	0.5
(IOL = 5.3 mA) $\overline{AS}$, D15–D0, $\overline{LDS}$, R/$\overline{W}$, $\overline{UDS}$		—	0.5	—	0.5
Current Dissipation* f = 0 Hz	I_D	—	0.7	—	1.0
f=10MHz		—	10	—	15
f=16 MHz		—	15	—	25
f= 20 MHz		—	20	—	30
Capacitance (Vin = 0 V, T_A = 25 °C, Frequency = 1 MHz)**	Cin	—	20.0	—	20.0
Load Capacitance $\overline{HALT}$	CL	—	70	—	70
All Others			130		130

*During normal operation, instantaneous Vcc current requirements may be as high as 1.5A.

Currents listed are with no loading.

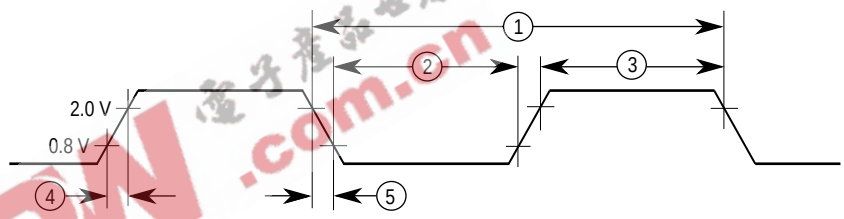
**Capacitance is periodically sampled rather than 100% tested.

6.0 MC68SEC000 AC ELECTRICAL SPECIFICATIONS — CLOCK TIMING (See Figure 2)

Add the following table and Figure 8 to Section 10.9 on page 10-9.

NUM.	CHARACTERISTIC	SYMBOL	10MHz		16MHz		20MHz	
			MIN	MAX	min	max	min	max
	Frequency of Operation	f	0	10.0	0	16.7	0	20.0
1	Cycle time	tcyc	100	—	60	—	50	—
2,3	Clock Pulse Width	t_{CL} t_{CH}	45 45	— —	27 27	— —	21 21	— —
4,5	Clock Rise and Fall Times	t_{Cr} t_{Cf}	— —	10 10	— —	5 5	— —	4 4

Applies to 3.3V and 5V.



NOTE: Timing measurements are referenced to and from a low voltage of 0.8 V and a high voltage of 2.0 V, unless otherwise noted. The voltage swing through this range should start outside and pass through the range such that the rise or fall will be linear between 0.8 V and 2.0 V.

Figure 8. MC68SEC000 Clock Input Timing Diagram

7.0 MC68SEC000 AC ELECTRICAL SPECIFICATIONS — READ AN WRITE CYCLES

Add the following table and Figures 9 and 10 to Section 10.16.

Applies to 3.3V and 5V.

(GND = 0 V; $T_A = T_L$ to T_H; see Figures 3 and 4)

NUM	CHARACTERISTIC	10MHz		16MHz		20MHz	
		MIN	MAX	MIN	MAX	MIN	MAX
6	Clock Low to Address Valid	—	35	—	30	—	25
6A	Clock High to FC Valid	0	35	0	30	0	25
7	Clock High to Address, Data Bus High Impedance (Maximum) (Write)	—	55	—	50	—	42
8	Clock High to Address, FC Invalid (Minimum)	0	—	0	—	0	—
9[1]	Clock High to $\overline{AS}$, $\overline{LDS}$, $\overline{UDS}$ Asserted	3	35	3	30	3	25
11[2]	Address Valid to $\overline{AS}$, $\overline{LDS}$, $\overline{UDS}$ Asserted (Read)/ $\overline{AS}$ Asserted (Write)	20	—	15	—	10	—
11A[2]	FC Valid to $\overline{AS}$, $\overline{LDS}$, $\overline{UDS}$ Asserted (Read)/ $\overline{AS}$ Asserted (Write)	45	—	45	—	40	—
12[1]	Clock Low to $\overline{AS}$, $\overline{LDS}$, $\overline{UDS}$ Negated	3	35	3	30	3	25
13[2]	$\overline{AS}$, $\overline{LDS}$, $\overline{UDS}$ Negated to Address, FC Invalid	15	—	15	—	10	—
14[2]	$\overline{AS}$ (and $\overline{LDS}$, $\overline{UDS}$ Read) Width Asserted	195	—	120	—	100	—
14A[2]	$\overline{LDS}$, $\overline{UDS}$ Width Asserted (Write)	95	—	60	—	50	—
15[2]	$\overline{AS}$, $\overline{LDS}$, $\overline{UDS}$ Width Negated	105	—	60	—	50	—
16	Clock High to Control Bus High Impedance	—	55	—	50	—	42
17[2]	$\overline{AS}$, $\overline{LDS}$, $\overline{UDS}$ Negated to R/$\overline{W}$ Invalid	15	—	15	—	10	—
18[1]	Clock High to R/$\overline{W}$ High (Read)	0	35	0	30	0	25
20[1]	Clock High to R/$\overline{W}$ Low (Write)	0	35	0	30	0	25
20A[2,6]	$\overline{AS}$ Asserted to R/$\overline{W}$ Low (Write)	—	10	—	10	—	10
21[2]	Address Valid to R/$\overline{W}$ Low (Write)	0	—	0	—	0	—
21A[2]	FC Valid to R/$\overline{W}$ Low (Write)	50	—	30	—	25	—
22[2]	R/$\overline{W}$ Low to $\overline{DS}$ Asserted (Write)	50	—	30	—	25	—
23	Clock Low to Data-Out Valid (Write)	—	35	—	30	—	25
25[2]	$\overline{AS}$, $\overline{LDS}$, $\overline{UDS}$ Negated to Data-Out Invalid (Write)	30	—	15	—	10	—
26[2]	Data-Out Valid to $\overline{LDS}$, $\overline{UDS}$ Asserted (Write)	30	—	15	—	10	—
27[5]	Data-In Valid to Clock Low (Setup Time on Read)	5	—	5	—	5	—
28[2]	$\overline{AS}$, $\overline{LDS}$, $\overline{UDS}$ Negated to $\overline{DTACK}$ Negated (Asynchronous Hold)	0	110	0	110	0	95
28A	Clock High to $\overline{DTACK}$ Negated	0	110	0	110	0	95

AC ELECTRICAL SPECIFICATIONS — READ AND WRITE CYCLES (Continued)

NUM	CHARACTERISTIC	10MHz		16MHz		20MHz	
		MIN	MAX	MIN	MAX	MIN	MAX
29	$\overline{AS}$, $\overline{LDS}$, $\overline{UDS}$ Negated to Data-In Invalid (Hold Time on Read)	0	—	0	—	0	—
29A	$\overline{AS}$, $\overline{LDS}$, $\overline{UDS}$ Negated to Data-In High Impedance (Read)	—	150	—	90	—	75
30	$\overline{AS}$, $\overline{LDS}$, $\overline{UDS}$ Negated to $\overline{BERR}$ Negated	0	—	0	—	0	—
31[2,5]	$\overline{DTACK}$ Asserted to Data-In Valid (Setup Time on Read)	—	65	—	50	—	42
32	$\overline{HALT}$ and $\overline{RESET}$ Input Transition Time	0	150	0	150	0	150
33	Clock High to $\overline{BG}$ Asserted	—	35	—	30	—	25
34	Clock High to $\overline{BG}$ Negated	—	35	—	30	—	25
35	$\overline{BR}$ Asserted to $\overline{BG}$ Asserted	1.5	3.5	1.5	3.5	1.5	3.5
36[7]	$\overline{BR}$ Negated to $\overline{BG}$ Negated	1.5	3.5	1.5	3.5	1.5	3.5
38	$\overline{BG}$ Asserted to Control, Address, Data Bus High Impedance ($\overline{AS}$ Negated)	—	55	—	50	—	42
39	$\overline{BG}$ Width Negated	1.5	—	1.5	—	1.5	—
44	$\overline{AS}$, $\overline{LDS}$, $\overline{UDS}$ Negated to $\overline{AVEC}$ Negated	0	55	0	50	0	42
47[5]	Asynchronous Input Setup Time	5	—	5	—	5	—
48[2,3]	$\overline{BERR}$ Asserted to $\overline{DTACK}$ Asserted	20	—	10	—	10	—
52	Data-In Hold from Clock High	0	—	0	—	0	—
53	Data-Out Hold from Clock High (Write)	0	—	0	—	0	—
55	R/$\overline{W}$ Asserted to Data Bus Impedance Change (Write)	20	—	10	—	0	—
56[4]	$\overline{HALT}$, $\overline{RESET}$ Pulse Width	10	—	10	—	10	—
58[7]	$\overline{BR}$ Negated to $\overline{AS}$, $\overline{LDS}$, $\overline{UDS}$, R/$\overline{W}$ Driven	1.5	—	1.5	—	1.5	—
58A[7]	$\overline{BR}$ Negated to FC Driven	1	—	1	—	1	—

Applies to 3.3V and 5V.

NOTES: 1. For a loading capacitance of less than or equal to 50 pF, subtract 5 ns from the value given in the maximum columns

2. Actual value depends on clock period.

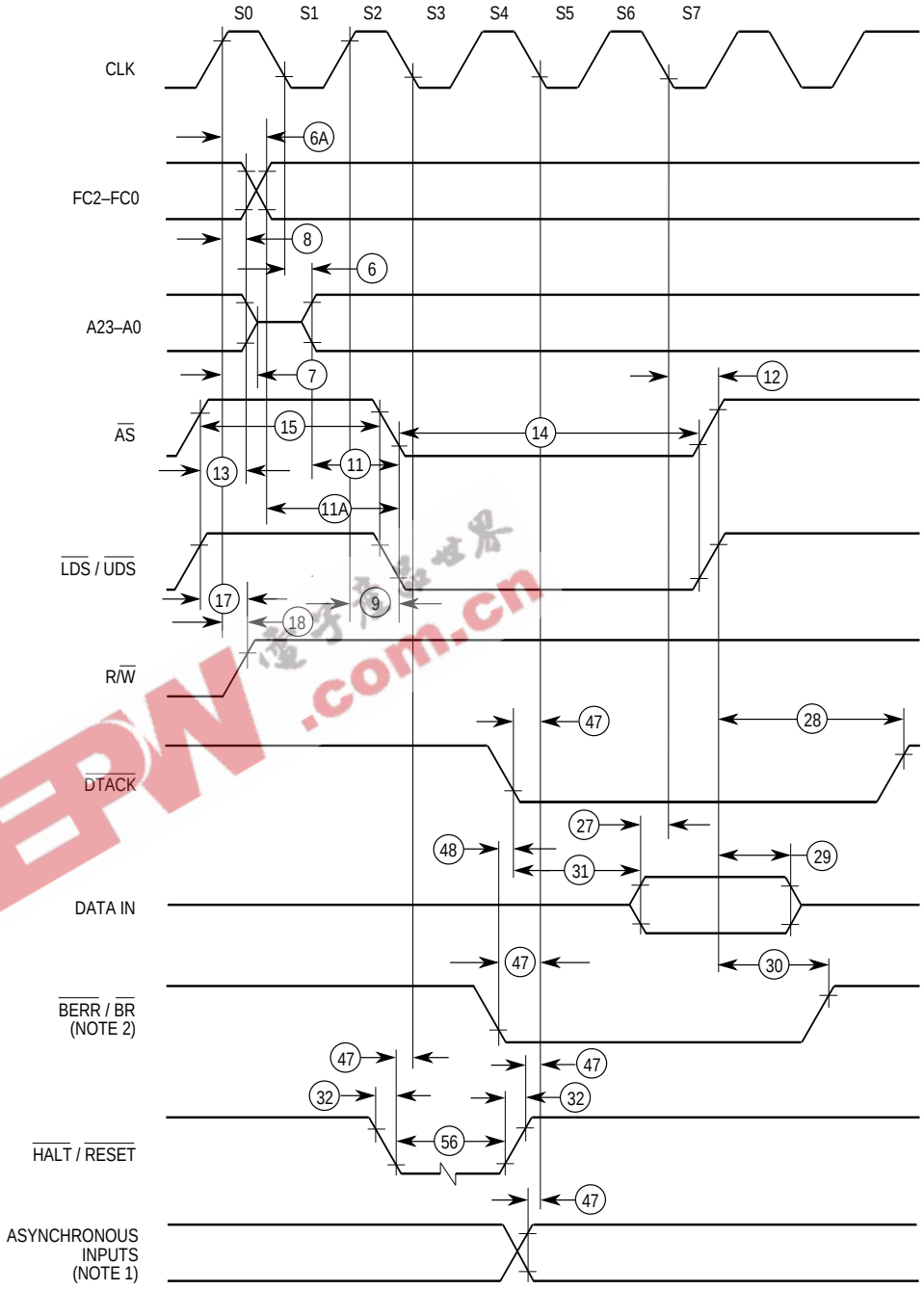
3. If #47 is satisfied for both $\overline{DTACK}$ and $\overline{BERR}$, #48 may be ignored. In the absence of $\overline{DTACK}$, $\overline{BERR}$ is an asynchron using the asynchronous input setup time (#47).

4. For power-up, the MC68SEC000 must be held in the reset state for 100 ms to allow stabilization of on-chip circuitry. A system is powered up, #56 refers to the minimum pulse width required to reset the controller.

5. If the asynchronous input setup time (#47) requirement is satisfied for $\overline{DTACK}$, the $\overline{DTACK}$ asserted to data setup tim requirement can be ignored. The data must only satisfy the data-in to clock low setup time (#27) for the following cloc

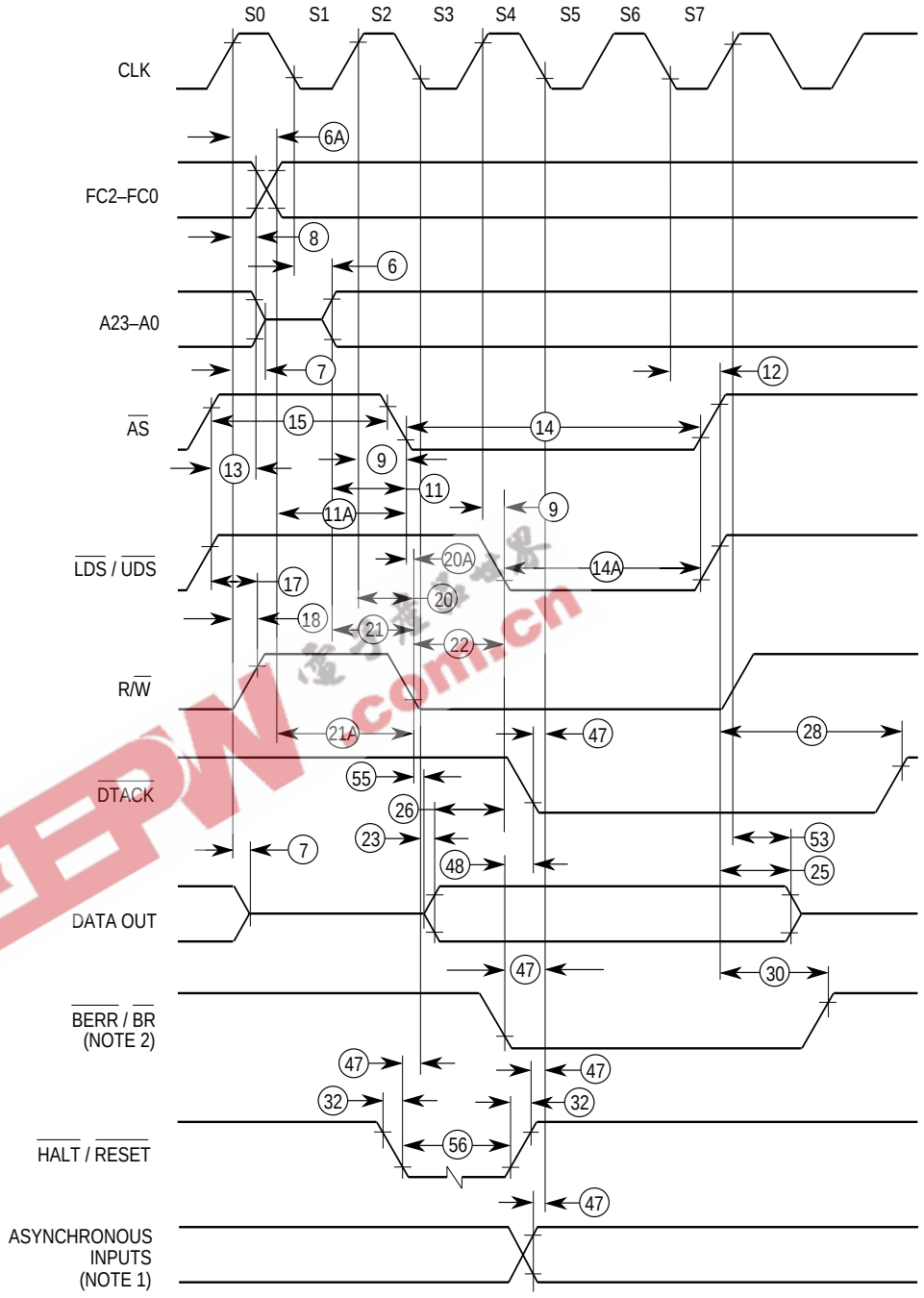
6. When $\overline{AS}$ and R/$\overline{W}$ are equally loaded (±20%), subtract 5 ns from the values given in these columns.

7. The minimum value must be met to guarantee proper operation. If the maximum value is exceeded, $\overline{BG}$ may be reass



NOTES:
1. Setup time for the asynchronous inputs $\overline{IPL2}$–$\overline{IPL0}$ and $\overline{AVEC}$ (#47) guarantees their recognition at the next falling edge of the clock.
2. $\overline{BR}$ need fall at this time only to insure being recognized at the end of the bus cycle.
3. Timing measurements are referenced to and from a low voltage of 0.8 V and a high voltage of 2.0 V, unless otherwise noted. The voltage swing through this range should start outside and pass through the range such that the rise or fall is linear between 0.8 V and 2.0 V.

Figure 9. MC68SEC000 Read Cycle Timing Diagram



NOTES:
1. Timing measurements are referenced to and from a low voltage of 0.8 V and a high voltage of 2.0 V, unless otherwise noted. The voltage swing through this range should start outside and pass through the range such that the rise or fall is linear between 0.8 V and 2.0 V.
2. Because of loading variations, R/$\overline{W}$ may be valid after $\overline{AS}$ even though both are initiated by the rising edge of S2 (specification #20A).

Figure 10. MC68SEC000 Write Cycle Timing Diagram

8.0 MC68SEC000 AC ELECTRICAL SPECIFICATIONS — BUS ARBITRATION

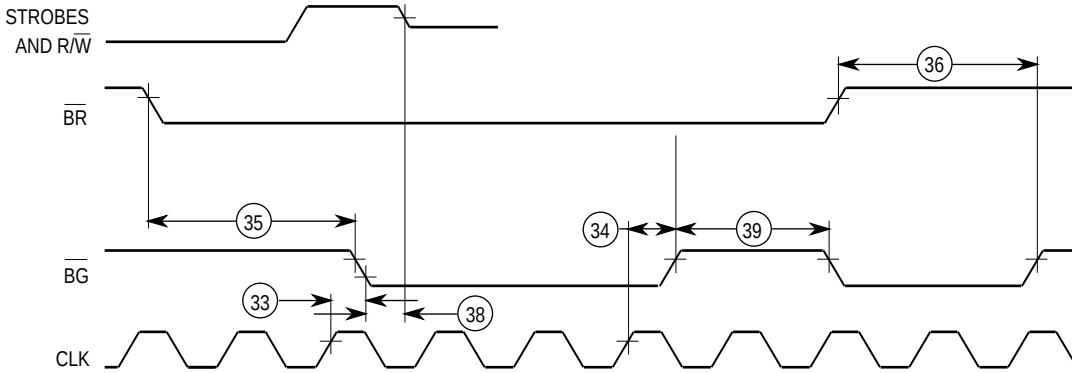
Add the following table and Figure 11 to Section 10.17.

(GND = 0 Vdc; $T_A = T_L$ to T_H; refer to Figure 13)

NUM	CHARACTERISTICp	10MHz		16MHz		20MHz	
		MIN	MAX	MIN	MAX	MIN	MAX
7	Clock High to Address, Data Bus High Impedance (Maximum)	—	55	—	50	—	42
16	Clock High to Control Bus High Impedance	—	55	—	50	—	42
33	Clock High to $\overline{BG}$ Asserted	0	35	0	30	0	25
34	Clock High to $\overline{BG}$ Negated	0	35	0	30	0	25
35	$\overline{BR}$ Asserted to $\overline{BG}$ Asserted	1.5	3.5	1.5	3.5	1.5	3.5
36	$\overline{BR}$ Negated to $\overline{BG}$ Negated	1.5	3.5	1.5	3.5	1.5	3.5
38	$\overline{BG}$ Asserted to Control, Address, Data Bus High Impedance ($\overline{AS}$ Negated)	—	55	—	50	—	42
39	$\overline{BG}$ Width Negated	1.5	—	1.5	—	1.5	—
47	Asynchronous Input Setup Time	5	—	5	—	5	—
58[1]	$\overline{BR}$ Negated to $\overline{AS}$, $\overline{LDS}$, $\overline{UDS}$, R/$\overline{W}$ Driven	1.5	—	1.5	—	1.5	—
58A[1]	$\overline{BR}$ Negated to FC Driven	1	—	1	—	1	—

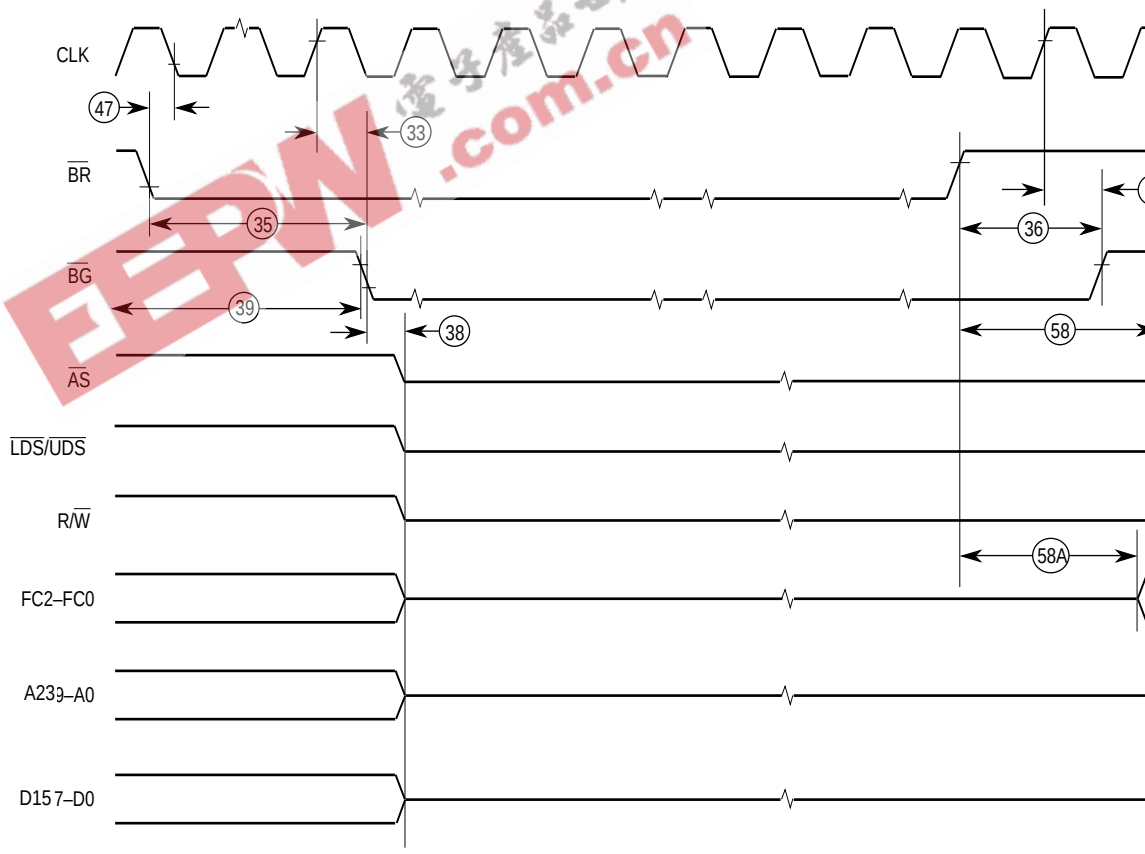
Applies to 3.3V and 5V.

1. The minimum value must be met to guarantee proper operation. If the maximum value is exceeded, $\overline{BG}$ may be reassert



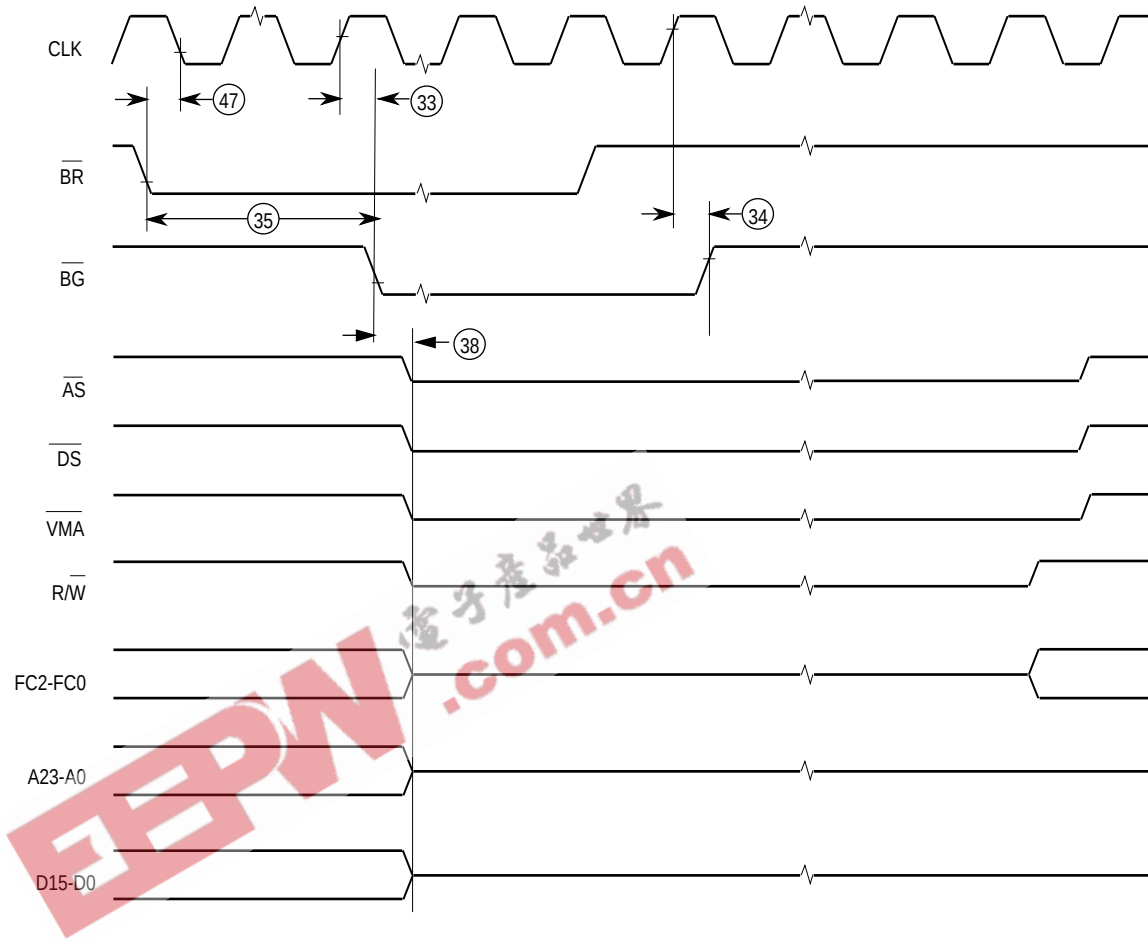
NOTE: Setup time to the clock (#47) for the asynchronous inputs BERR, BR, DTACK, IPL2-IPL0, and VPA guarantees their recognition at the next falling edge of the clock.

Figure 11. Bus Arbitration Timing



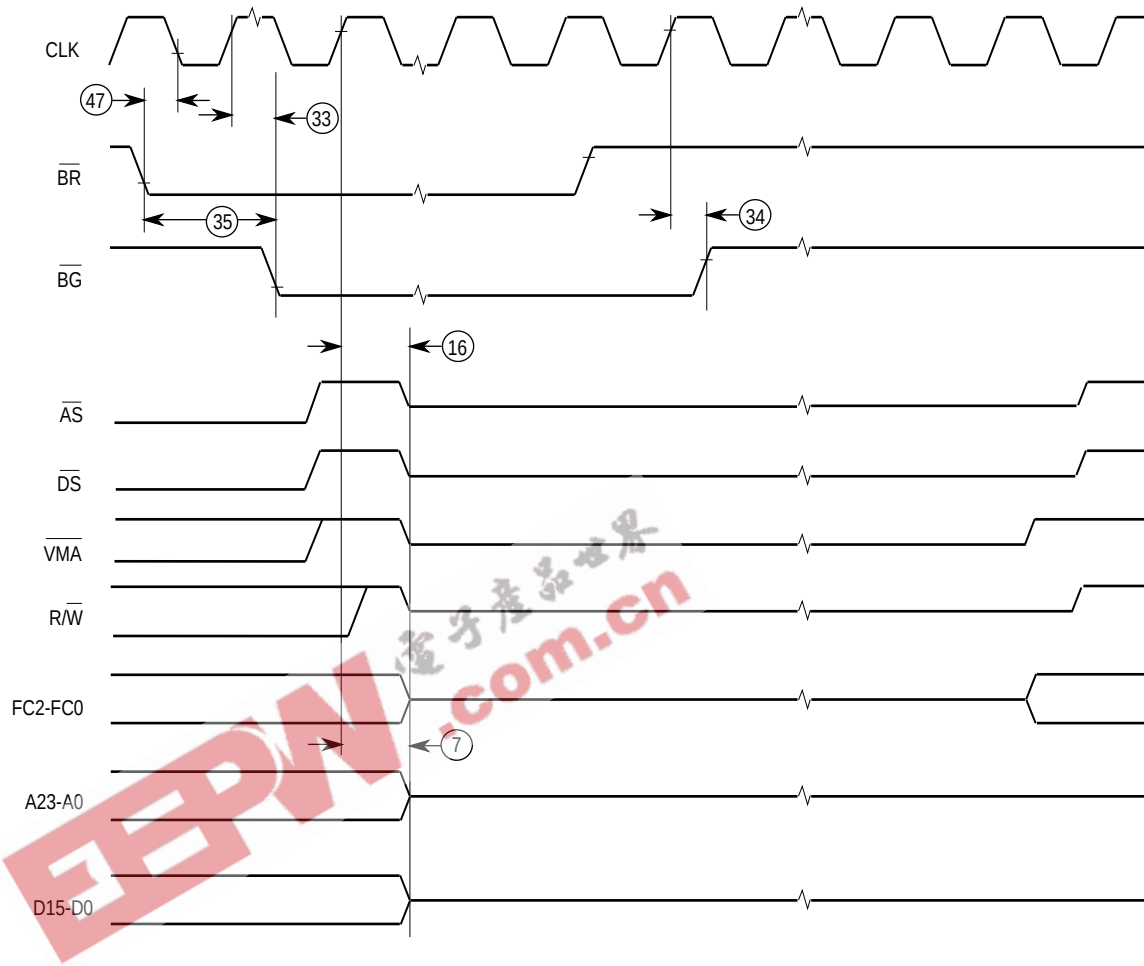
NOTE: Waveform measurements for all inputs and outputs are specified at: logic high 2.0 V, logic low = 0.8 V.

Figure 12. MC68SEC000 Bus Arbitration Timing Diagram



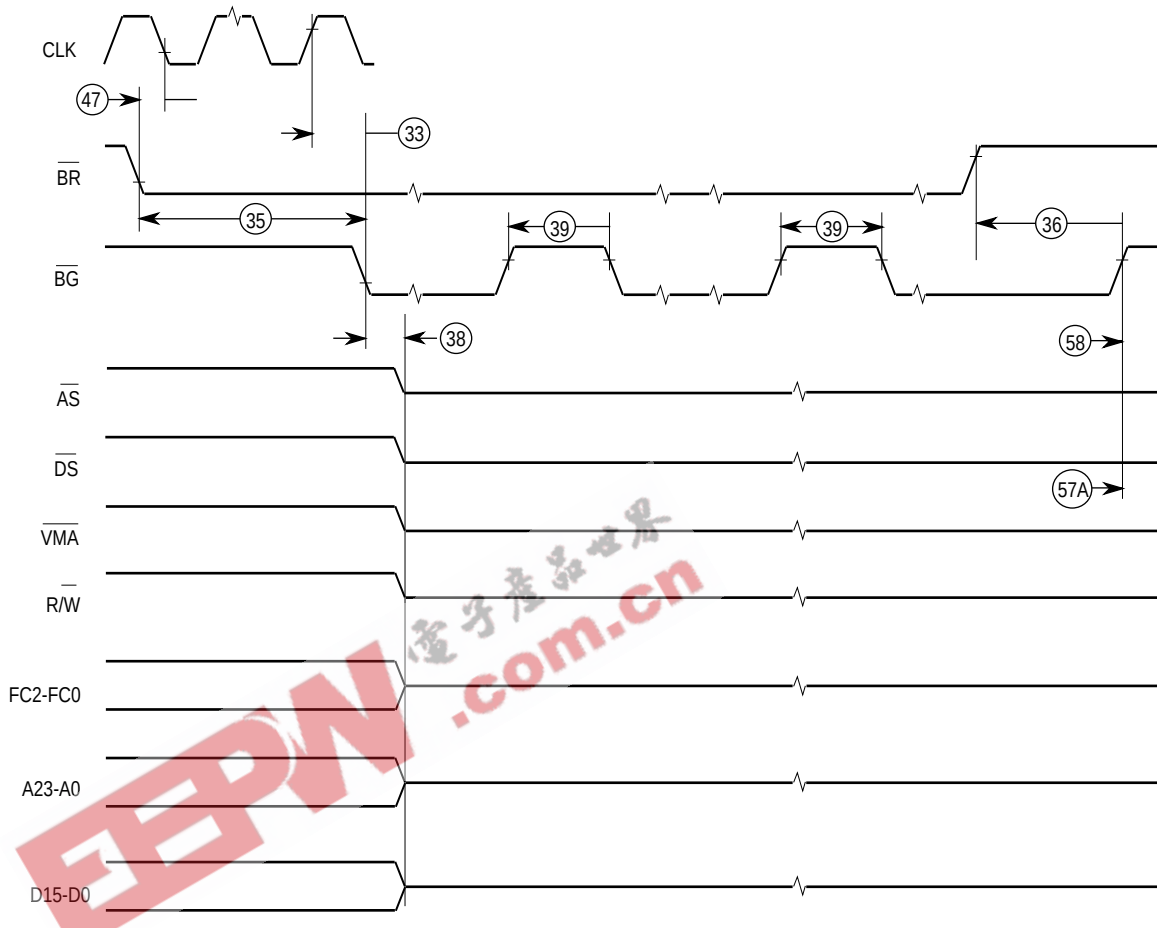
NOTES: Waveform measurements for all inputs and outputs are specified at: logic high 2.0 V, logic low = 0.8 V. This diagram also applies to the 6

Figure 13. Bus Arbitration Timing—Idle Bus Case



NOTE: Waveform measurements for all inputs and outputs are specified at: logic high 2.0 V, logic low = 0.8 V.
This diagram also applies to the 68EC000.

Figure 14. Bus Arbitration Timing - Active Bus Case



NOTES: Waveform measurements for all inputs and outputs are specified at: logic high 2.0 V, logic low = 0.8 V.
This diagram also applies to the 68EC000.

Figure 15. Bus Arbitration - Multiple Bus Request

9.0 MECHANICAL DATA

9.1 PIN ASSIGNMENTS

Add Figure 12 to Section 11.1.

The following defines the pin assignment and the package dimensions of the 64 lead QFP (FU pac
and 64 lead TQFP (PB package) for the MC68SEC000. Note that it is pin-to-pin compatible with th
MC68EC000.

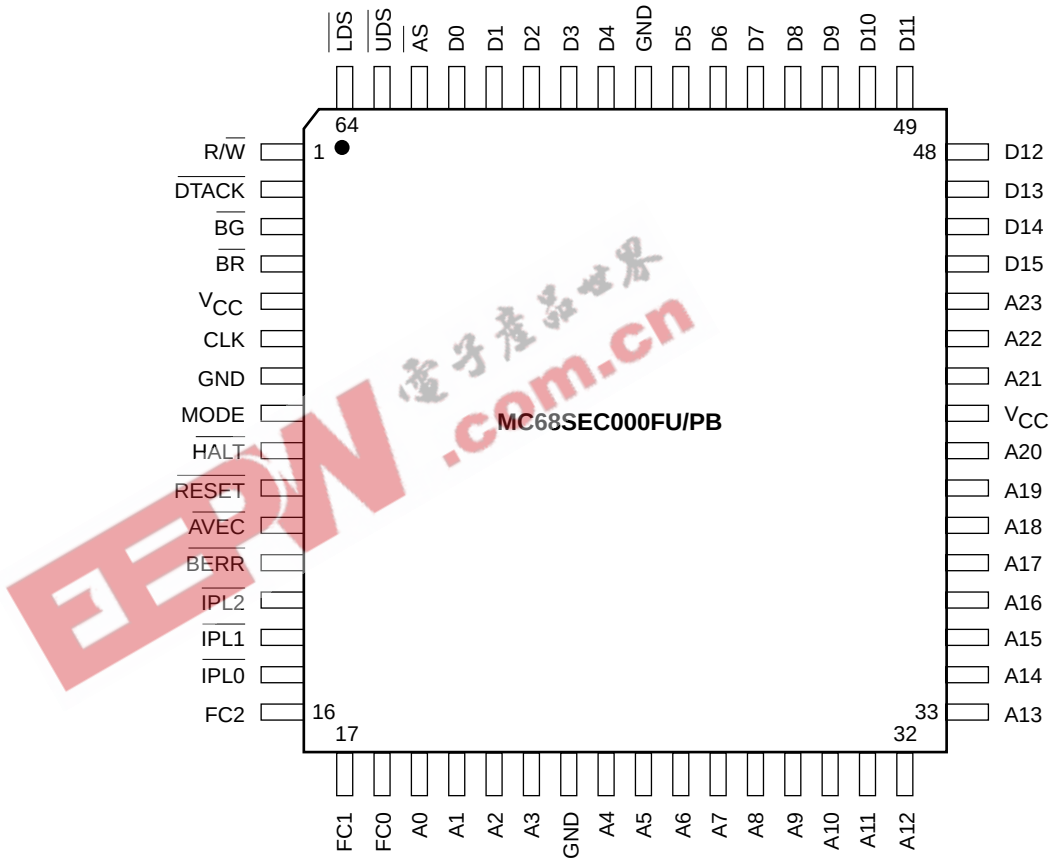
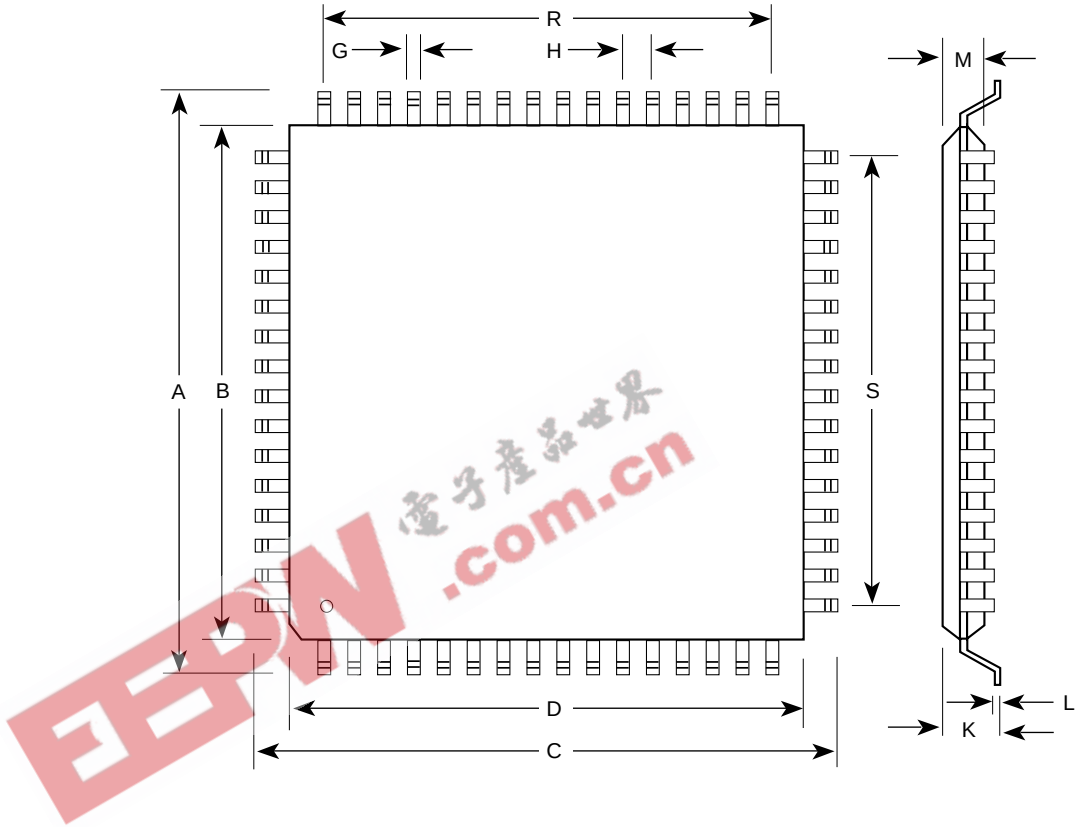


Figure 16. 64-Lead Quad Flat Pack and 64-Lead Thin Quad Flat Pack

10.0 PACKAGE DIMENSIONS - FU SUFFIX

This diagram replaces the one on Page 11-16

64 Lead Quad Flat Pack Case 840B-01

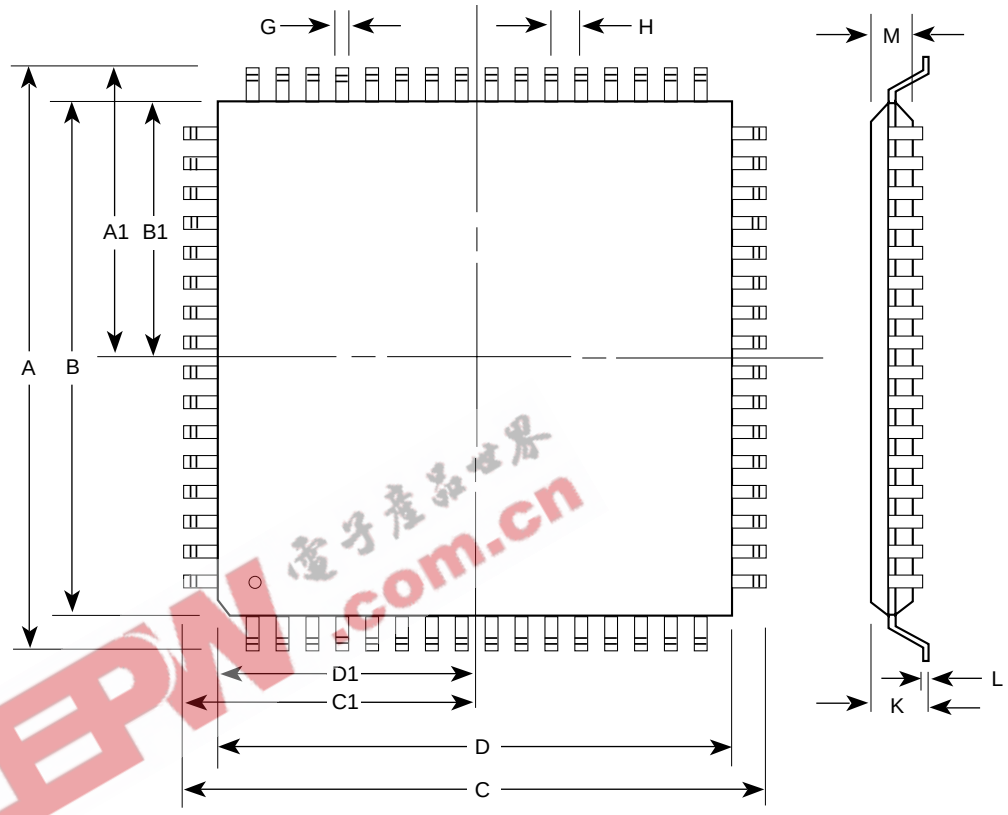


DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	16.95	17.45	0.667	0.687
B	13.90	14.10	0.547	0.555
C	16.95	17.45	0.667	0.687
D	13.90	14.10	0.547	0.555
G	0.30	0.45	0.012	0.018
H	0.80 BSC		0.031 BSC	
K	2.15	2.45	0.085	0.096
L	0.13	0.23	0.005	0.009
M	2.00	2.40	0.79	0.094
R	12.00 REF		0.472 REF	
S	12.00 REF		0.472 REF	

11.0 PACKAGE DIMENSIONS - PB SUFFIX

Add the following to Section 11.2.

64 Lead Thin Quad Flat Pack Case 840F-02



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	12.00 BSC		0.472 BSC	
A1	6.00 BSC		0.236 BSC	
B	10.00 BSC		0.394 BSC	
B1	5.00 BSC		0.197 BSC	
C	12.00 BSC		0.472 BSC	
C1	6.00 BSC		0.236 BSC	
D	10.00 BSC		0.394 BSC	
D1	5.00 BSC		0.197 BSC	
G	0.17	0.27	0.007	0.011
H	0.50 BSC		0.020 BSC	
K	---	1.60	---	0.063
L	0.09	0.20	0.004	0.008
M	1.35	1.45	0.053	0.057

12.0 PACKAGE/FREQUENCY AVAILABILITY

Replaces Section 11.1

The following tables identify the packages and operating frequencies available for the MC68HC000 MC68HC001, MC68EC000, and the MC68SEC000.

MC68SEC000 PACKAGE	FREQUENCY	VOLTAGE	
		3.3 V	5 V
Quad Flat Pack (FU)	10 MHz	✓	✓
	16 MHz	✓	✓
	20MHz	✓	✓
Thin Quad Flat Pack (PB)	10 MHz	✓	✓
	16 MHz	✓	✓
	20MHz	✓	✓

MC68HC000 PACKAGE	FREQUENCY	VOLTAGE 5V
Plastic DIP	8,10,12,16,20 MHz	3
Plastic Quad Pack (PLCC)	8,10,12,16,20 MHz	3
Plastic Quad (Gull Wing)**	8,10,12,16,20 MHz	3
Pin Grid Array, Solder Lead Finish**	8,10,12,16,20 MHz	3
Pin Grid Array, Gold Lead Finish**	8,10,12,16,20 MHz	3
Plastic Quad Pack (PLCC)	8,10,12,16,20 MHz	3

MC68HC001** PACKAGE	FREQUENCY	VOLTAGE 5V
Plastic Quad Pack (PLCC)	8,10,12,16 MHz	✓
Plastic Quad (Gull Wing)	8,10,12,16 MHz	✓
Pin Grid Array, Gold Lead Finish	8,10,12,16 MHz	✓
	8,10,12,16 MHz	✓

MC68EC000 PACKAGE	FREQUENCY	VOLTAGE 5V
Plastic Quad Pack (PLCC)	8 MHz	✓
Plastic Quad Flat Pack	10 MHz	✓
	12 MHz	✓
	16 MHz	✓
	20 MHz	✓

NOTE : ** not recommended for new designs

ORDERING INFORMATION

Add the following to Section 11.

The following tables contains the ordering information for the MC68SEC000.

MC68SEC000 Ordering Information

PACKAGE	BODY SIZE	LEAD SPACING	SPEED (IN MH Z)	VOLTAGE	SUFFIX	TEMPER RAN
QFP	14.0 mm X 14.0mm	0.8mm	10/16/20 MHz	3.3V or 5.0V	FU	0C to +
					CFU	-40C to
TQFP	10.0mm x 10.0mm	0.5mm			PB	0C to +
					CPB	-40C to

MC68HC000 Ordering Information

PACKAGE	BODY SIZE	LEAD SPACING	SPEED (IN MHZ)	VOLTAGE	SUFFIX	TEMPER RAN
DIP	81.91mm X 20.57mm	2.54mm	8, 10, 12, 16	5.0V	P	0C to
PLCC	25.57mm X 25.27mm	1.27mm	8, 10, 12, 16, 20		FN	0C to
			8, 10, 12, 16		CFN	-40C to

MC68EC000 Ordering Information

PACKAGE	BODY SIZE	LEAD SPACING	SPEED (IN MHZ)	VOLTAGE	SUFFIX	TEMPER RAN
PLCC	25.57mm X 25.27mm	1.27mm	8, 10,12, 16, 20	5.0V	FN	0C to
PQFP	14.1mm X 14.1mm	0.8mm	8, 10,12, 16, 20		FU	

DOCUMENTATION

Add to Section 11.

The documents listed in the following table contain detailed information that pertain to the MC68SE processor. You can obtain these documents from the Literature Distribution Centers listed on the la of this document.

MC68SEC000 Documentation

MC68SEC000 DOCUMENTATION	DOCUMENT NUMBER
M68000 Family Programmer's Reference Manual	M68000PM/AD
M68000 User's Manual	M68000UM/AD
High Performance Embedded Systems Source Catalog"	BR729/D
MC68EC000 Product Brief	MC68EC000/D
MC68SEC000 Product Brief	MC68SEC000/D

Literature Distribution Centers:
USA/EUROPE: Motorola Literature Distribution; P.O. Box 20912, Arizona 85036.
JAPAN: Nippon Motorola Ltd.; 4-32-1, Nishi-Gotanda, Shinagawa-ku, Tokyo 141 Japan.
ASIA-PACIFIC: Motorola Semiconductors H.K. Ltd.; Silicon Harbour Center, No. 2 Dai King Street, Tai Po Industrial Estate, Tai Po, N.T., Hong Kong.